

## P-Channel Enhancement Mode Power MOSFET

### Description

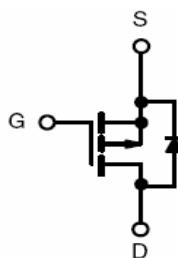
The PE60P25K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge .This device is well suited for high current load applications.

### General Features

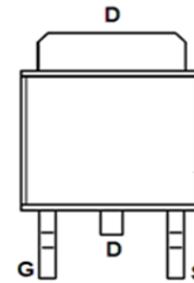
- $V_{DS} = -60V, I_D = -25A$
- $R_{DS(ON)} < 45m\Omega @ V_{GS} = -10V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

### Application

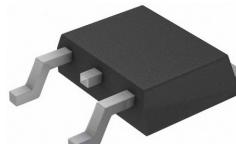
- High side switch for full bridge converter
- DC/DC converter for LCD display



Schematic diagram



Marking and pin assignment



TO-252 -2Ltop view

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-25	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	-17.7	A
Pulsed Drain Current	$I_{DM}$	-60	A
Maximum Power Dissipation	$P_D$	90	W
Derating factor		0.72	W/ $^\circ C$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	300	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

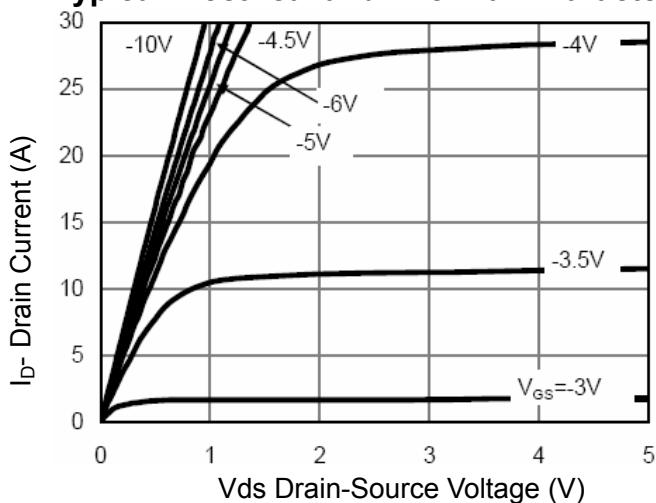
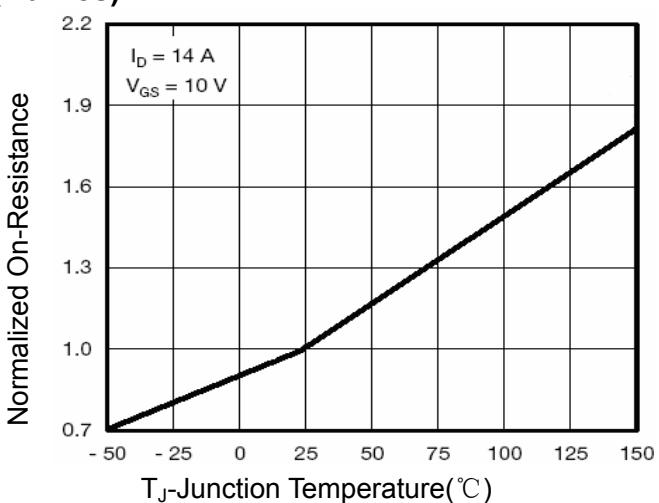
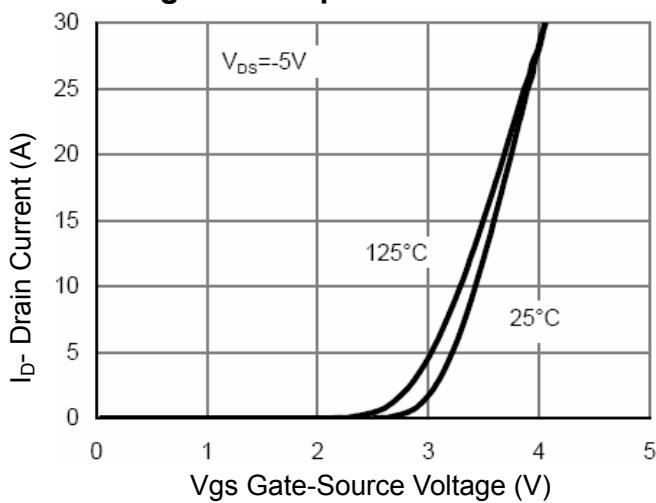
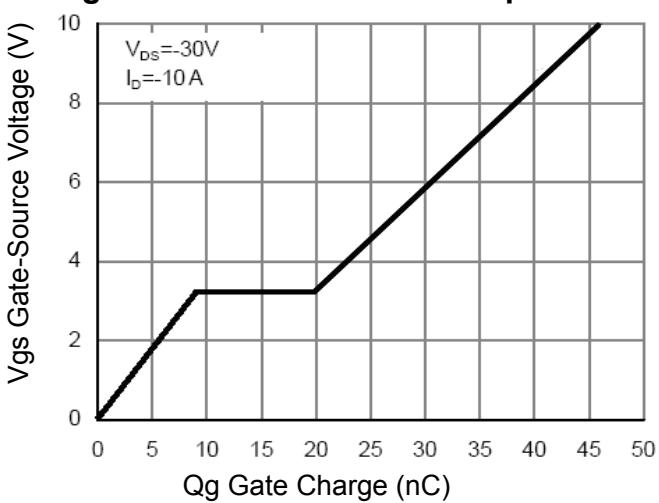
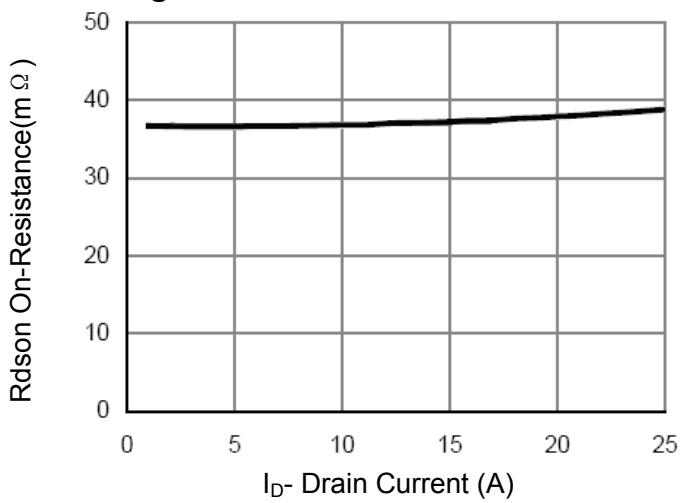
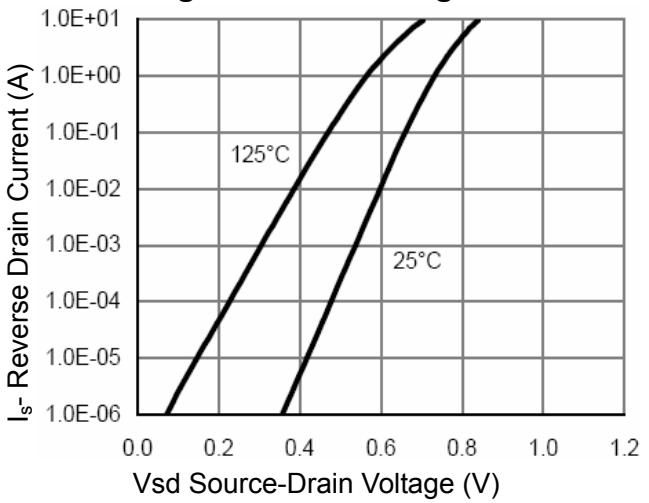
Thermal Resistance, Junction-to-Case(Note 2)	$R_{\theta JC}$	1.4	$^\circ C/W$
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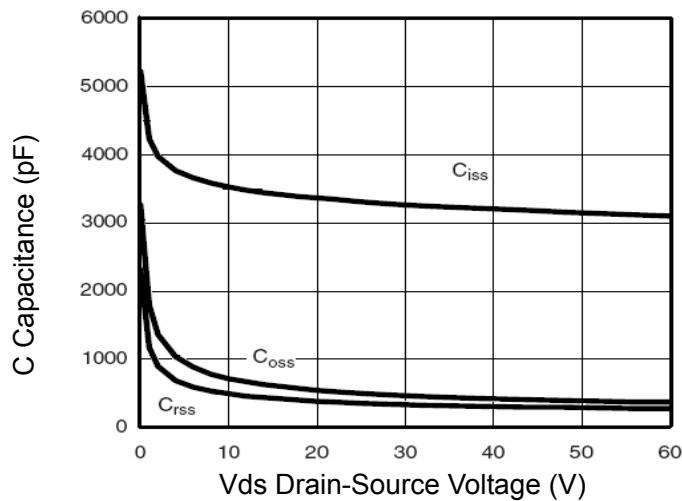
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-60	-	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=-60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$	-2	-2.6	-3.5	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-20\text{A}$	-	37	45	$\text{m}\Omega$
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-10\text{A}$	-	25	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=-30\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	3430	-	PF
Output Capacitance	$\text{C}_{\text{oss}}$		-	391	-	PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	272	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=-30\text{V}, \text{R}_L=1.5\Omega,$ $\text{V}_{\text{GS}}=-10\text{V}, \text{R}_G=3\Omega$	-	12	-	nS
Turn-on Rise Time	$t_r$		-	15	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	38	-	nS
Turn-Off Fall Time	$t_f$		-	15	-	nS
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=-30, \text{I}_D=-20\text{A},$ $\text{V}_{\text{GS}}=-10\text{V}$	-	46	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	9.5	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	10.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=-10\text{A}$	-		-1.2	V
Diode Forward Current (Note 2)	$\text{I}_S$		-	-	-25	A
Reverse Recovery Time	$t_{\text{rr}}$	$\text{T}_J = 25^\circ\text{C}, \text{IF} = -10\text{A}$ $\text{di}/\text{dt} = -100\text{A}/\mu\text{s}(\text{Note 3})$	-	47	-	nS
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	53	-	nC
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

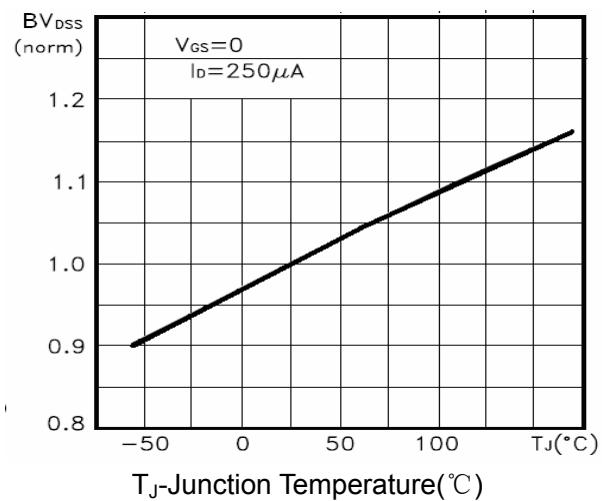
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition:  $\text{T}_J=25^\circ\text{C}, \text{V}_{\text{DD}}=-20\text{V}, \text{V}_G=-10\text{V}, \text{L}=1\text{mH}, \text{R}_G=25\Omega, \text{I}_{\text{AS}}=33\text{A}$

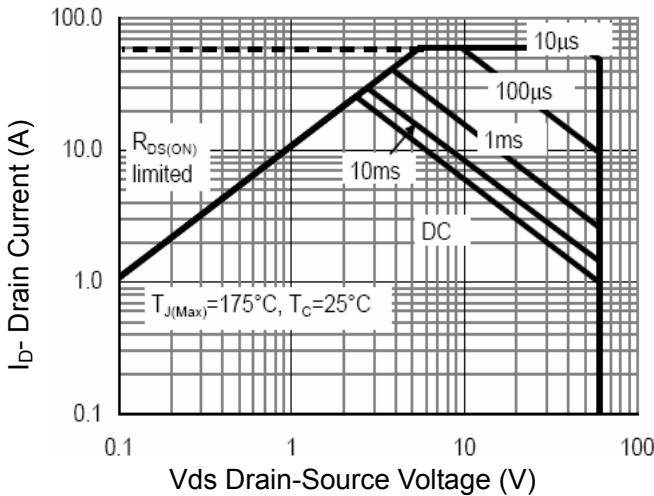
**Typical Electrical and Thermal Characteristics (Curves)****Figure 1 Output Characteristics****Figure 4 Rdson-Junction Temperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson-Drain Current****Figure 6 Source-Drain Diode Forward**



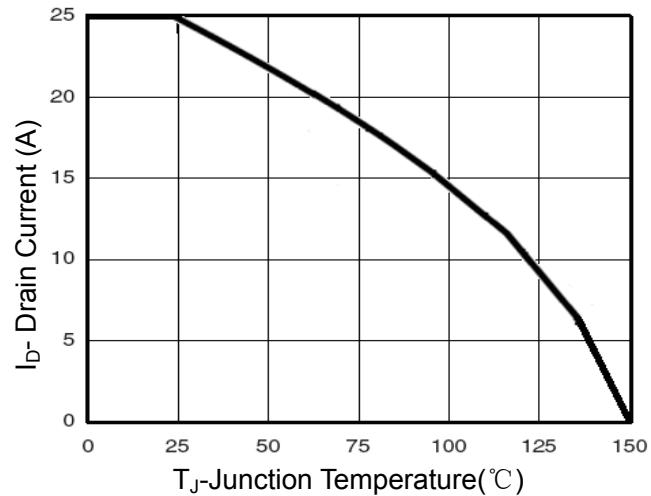
**Figure 7 Capacitance vs Vds**



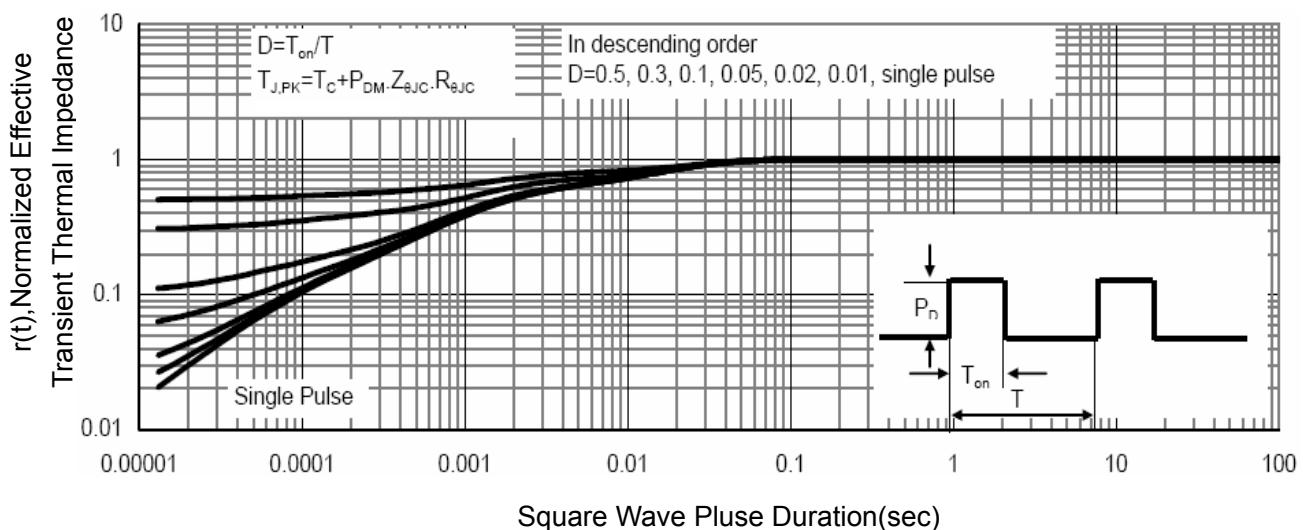
**Figure 9 BV<sub>DSS</sub> vs Junction Temperature**



**Figure 8 Safe Operation Area**

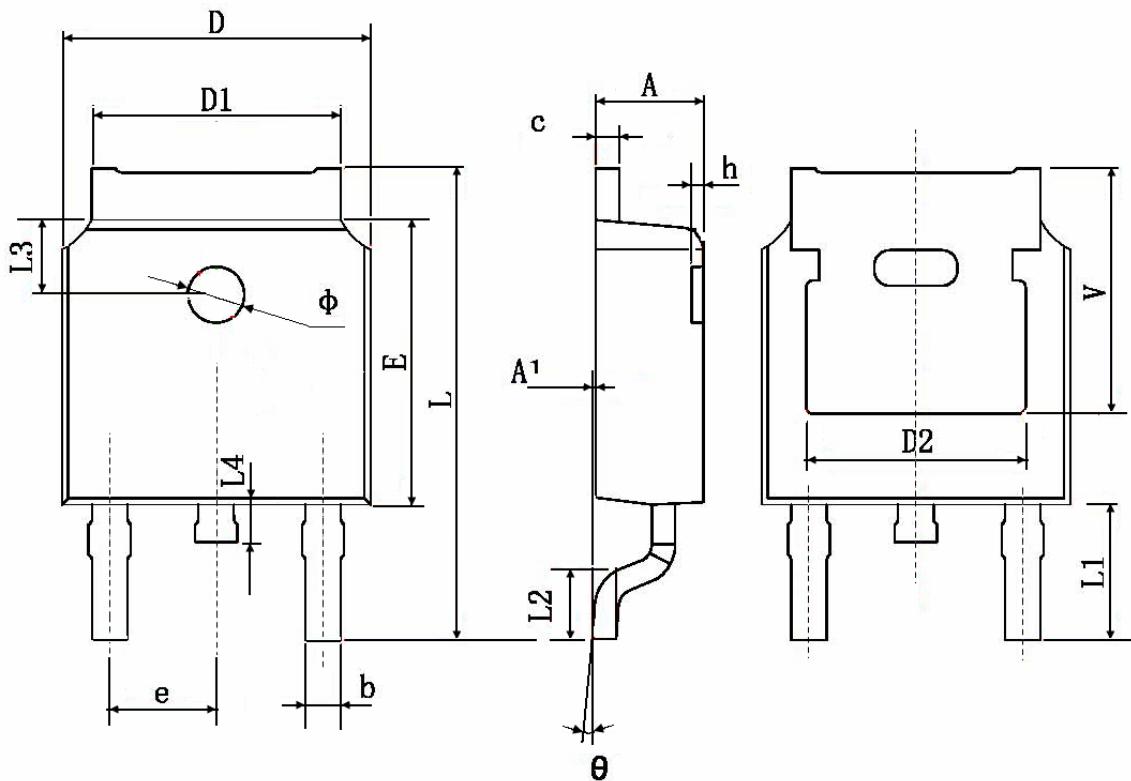


**Figure 10 ID Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	